Product Change Notification

Change Notification #:	**118893-00**
Change Title:	**2U 12x3.5inch SAS and 2x NVMe Hot Swap Backplane F2U12X35S3PH, 1U 8x2.5 inch SAS/NVMe Hot Swap Backplane F1U8X25S3PHS, 2U Hot-swap 8x2.5inch SAS/NVMe Combo Drive Bay Kit A2U8X25S3PHS, PCN 118893-00, Product Material, New Alternate Hot Swap Backplane**
Date of Publication:	**February 03, 2022**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	March 11, 2022

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the items listed in the “Products Affected” table.

Adding a second source for a Voltage Regulator (VR) controller on the Hot swap backplanes (HSBP). The new controller is identical in function to the previous one but differs in form factor.

The interposer PCB supporting a new Programmable System-On-Chip (PSOC) is also being used in this version.
The new components have passed all functional and electrical validation tests successfully.
As a result, we are adding as alternates the following PBA in the Hot swap backplanes:

A2U8X25S3PHS - H88386-311
F2U12X35S3PH - H88392-411
F1U8X25S3PHS - H88382-411

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
2U Hot-swap 8x2.5inch SAS/NVMe Combo Drive Bay Kit A2U8X25S3PHS, Single	A2U8X25S3PHS	955858	J12659-007	H88386-252 H88386-253	J12659-008	H88386-252 H88386-253 H88386-311
1U 8x2.5 inch SAS/NVMe Hot Swap Backplane F1U8X25S3PHS, Single	F1U8X25S3PHS	955868	J11107-007	H88382-351 H88382-352	J11107-008	H88382-351 H88382-352 H88382-411
2U 12x3.5inch SAS and 2x NVMe Hot Swap Backplane F2U12X35S3PH, Single	F2U12X35S3PH	955869	J10383-005	H88392-351	J10383-006	H88392-351 H88392-411

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 03, 2022	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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